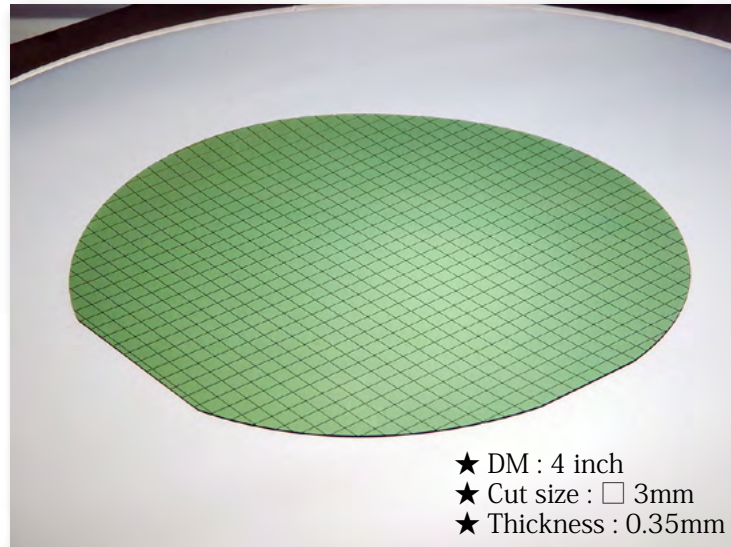




SoundCutting application

<Full Cutting of SiC wafer for semiconductor>



- ★ DM : 4 inch
- ★ Cut size : □ 3mm
- ★ Thickness : 0.35mm

Semiconductor wafer • SiC (Silicon Carbide) full cutting



- ★ Surface Al
- ★ Wafer SiC

Radial full cutting of aluminum sputtered SiC wafer

- Wear resistance of blade increases
- Prevention of big chipping
- High speed cutting of difficult-to-cut materials
- No damages
- Yield rate 100%

